



Material Content Data Sheet



Sales Product Name				IPU50R3K0CE		Issued		26. September 2017	
MA#				MA001023748					
Package				PG-TO251-3-341		Weight*		380.48 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.853	0.22	0.22	2242	2242	
leadframe	non noble metal	iron	7439-89-6	0.229	0.06		603		
	inorganic material	phosphorus	7723-14-0	0.069	0.02		181		
	non noble metal	copper	7440-50-8	228.946	60.19	60.27	601730	602514	
wire	non noble metal	aluminium	7429-90-5	0.142	0.04	0.04	372	372	
encapsulation	inorganic material	antimonytrioxide	1309-64-4	1.757	0.46		4618		
	plastics	brominated resin	-	1.883	0.49		4948		
	organic material	carbon black	1333-86-4	2.008	0.53		5278		
	plastics	epoxy resin	-	16.943	4.45		44530		
	inorganic material	silicondioxide	60676-86-0	102.912	27.05	32.98	270481	329855	
leadfinish	non noble metal	tin	7440-31-5	3.740	0.98	0.98	9830	9830	
plating	non noble metal	nickel	7440-02-0	0.509	0.13	0.13	1337	1337	
solder	noble metal	silver	7440-22-4	0.032	0.01		85		
	non noble metal	tin	7440-31-5	0.026	0.01		68		
	non noble metal	lead	7439-92-1	1.229	0.32	0.34	3229	3382	
heatspreader	non noble metal	iron	7439-89-6	0.019	0.00		50		
	inorganic material	phosphorus	7723-14-0	0.006	0.00		15		
	non noble metal	copper	7440-50-8	19.177	5.04	5.04	50403	50468	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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